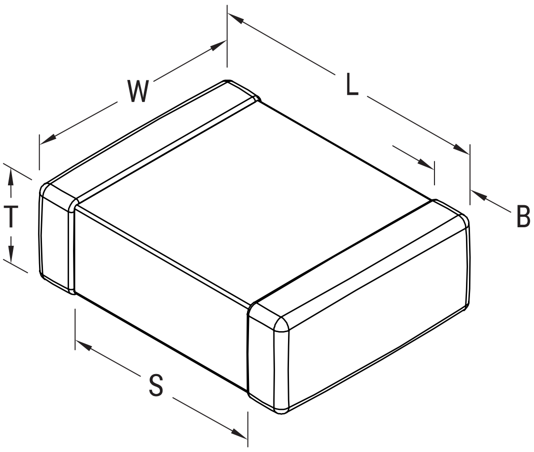
C2220C273M5TAC7210

SMD Comm X8G HT150C, Ceramic, 0.027 uF, 20%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	190 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	2220
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	1.4mm +/-0.15mm
S	3.5mm MIN
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	0.027 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	37.037 GOhms

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